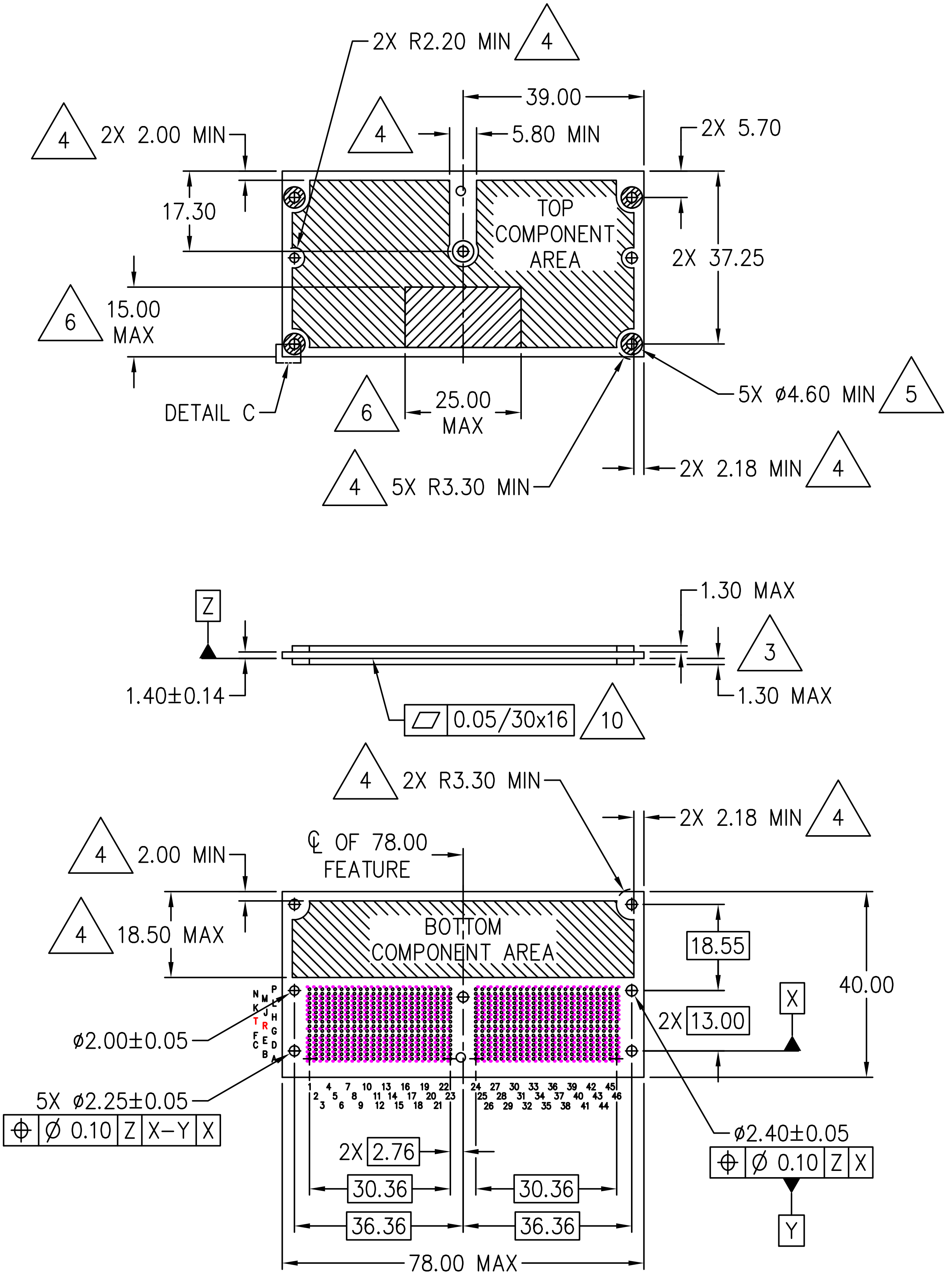
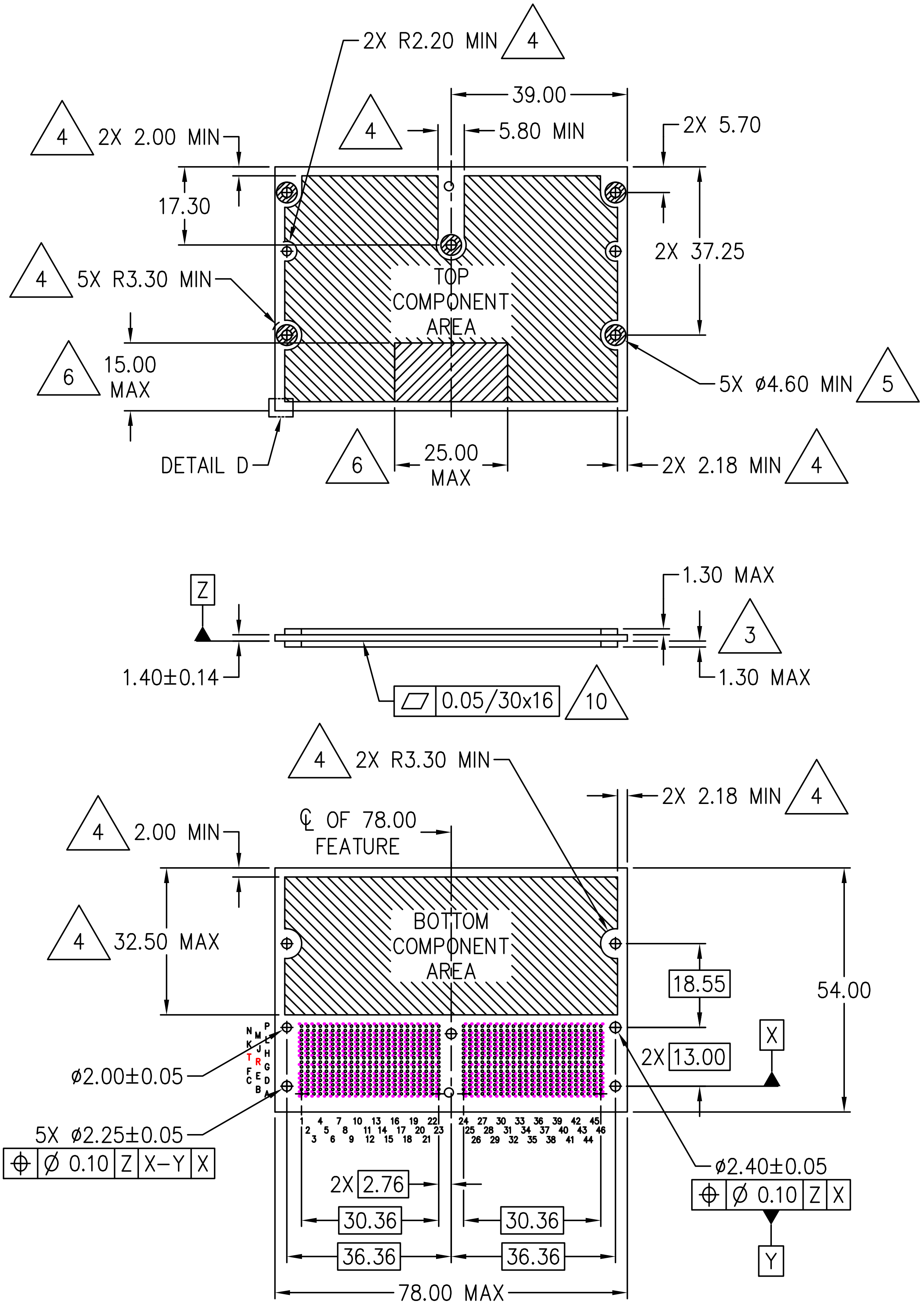


VARIATION AXXX

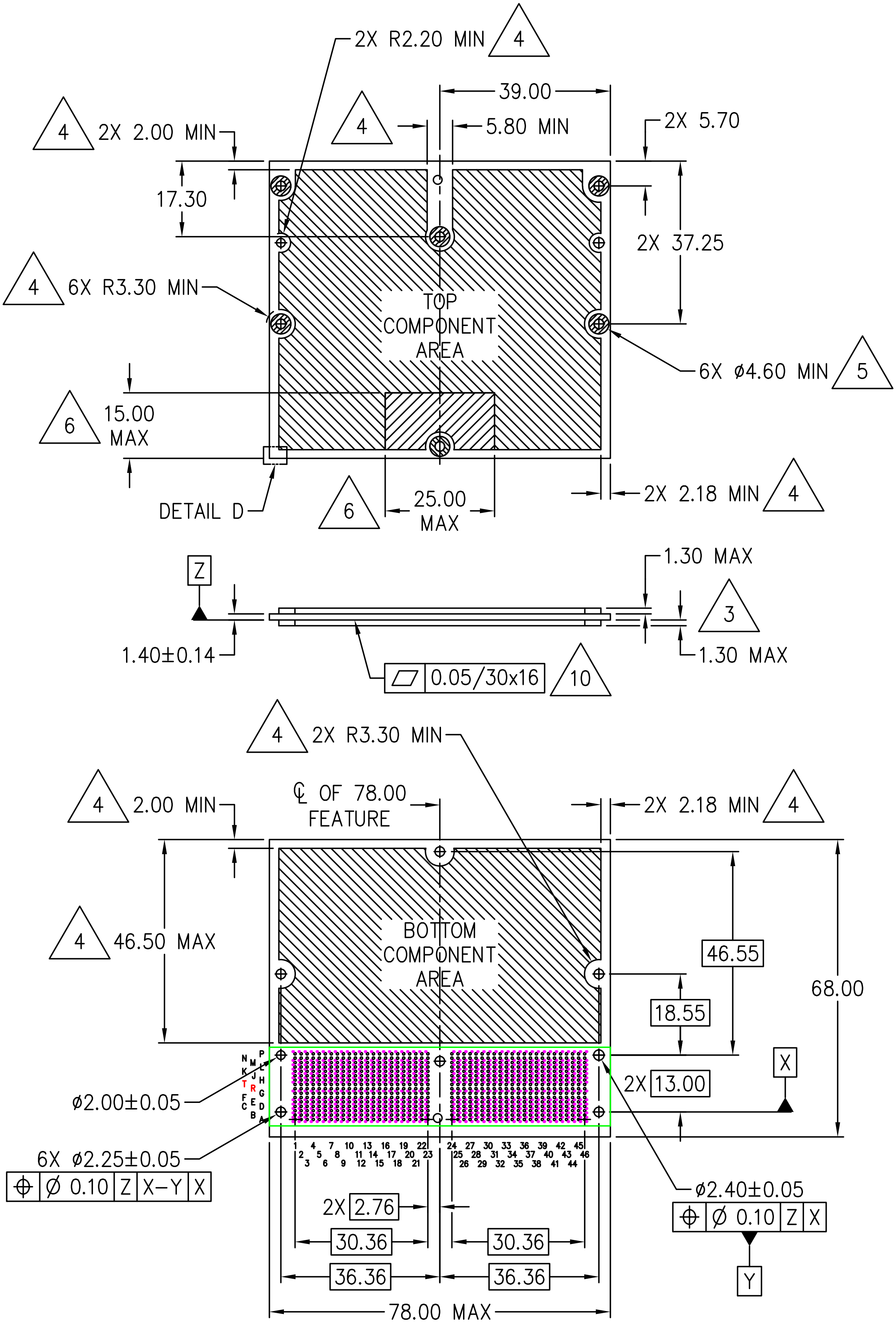
JEDEC SOLID STATE PRODUCT OUTLINE	THIS *REGISTERED OUTLINE* WAS PREPARED BY THE JEDEC JC-11 COMMITTEE AND REFLECTS A PRODUCT FOR ANTICIPATED USE IN THE ELECTRONICS INDUSTRY. CHANGES ARE LIKELY TO OCCUR. USERS ASSUME ALL RISK AND LIABILITY RESULTING FROM THE USE OF THIS OUTLINE.

TITLE	PACKAGE DESIGNATOR	NUMBER	ISSUE	DATE	SHEET
DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	XBMA-N#_I1p0_ ...	MO-358	C	AUG 2025	1 OF 10



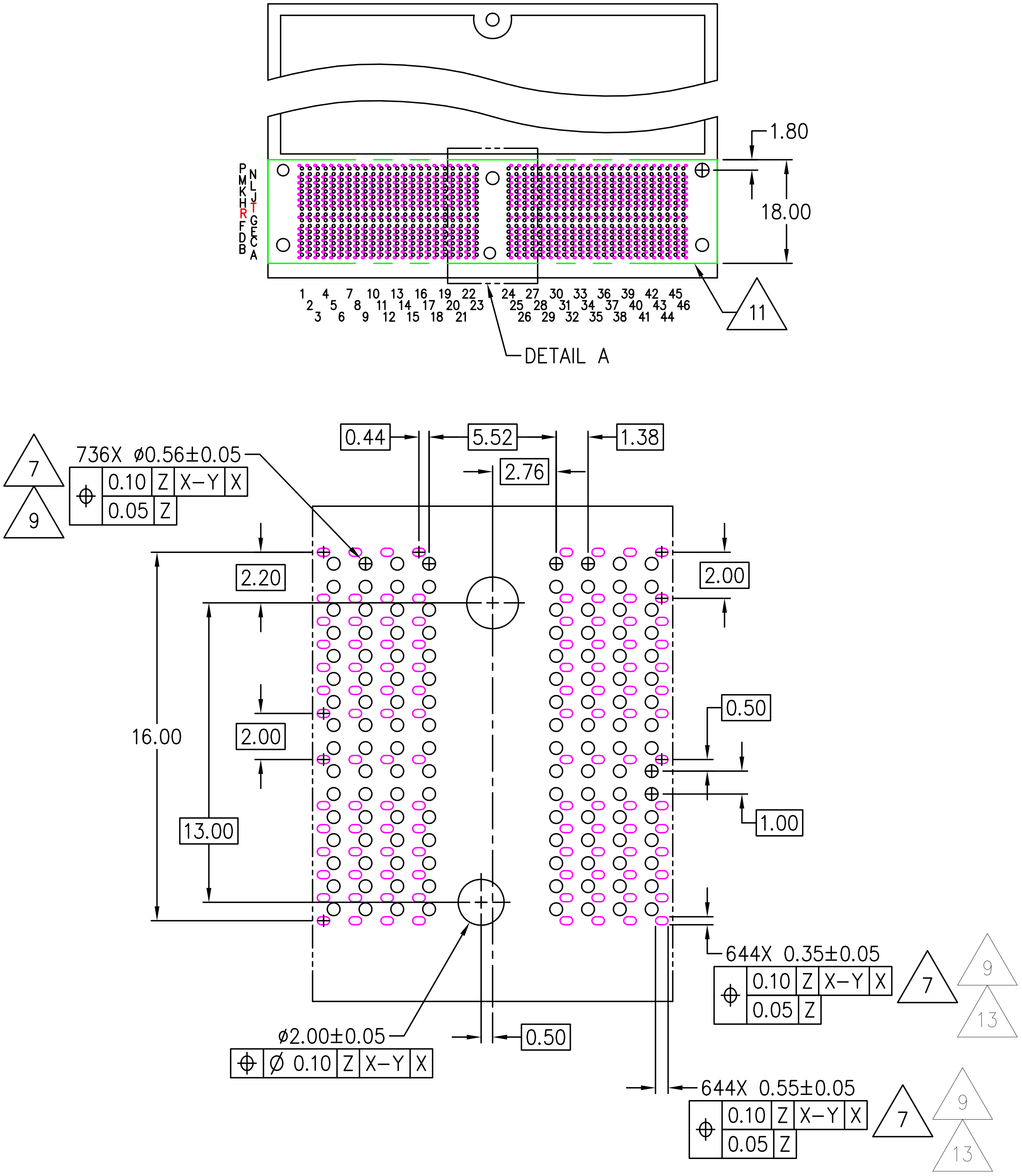
VARIATION BXXX

JEDEC SOLID STATE PRODUCT OUTLINE 	TITLE DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	NUMBER MO-358	ISSUE C	DATE AUG 2025	SHEET 2 OF 10



VARIATION CXXX

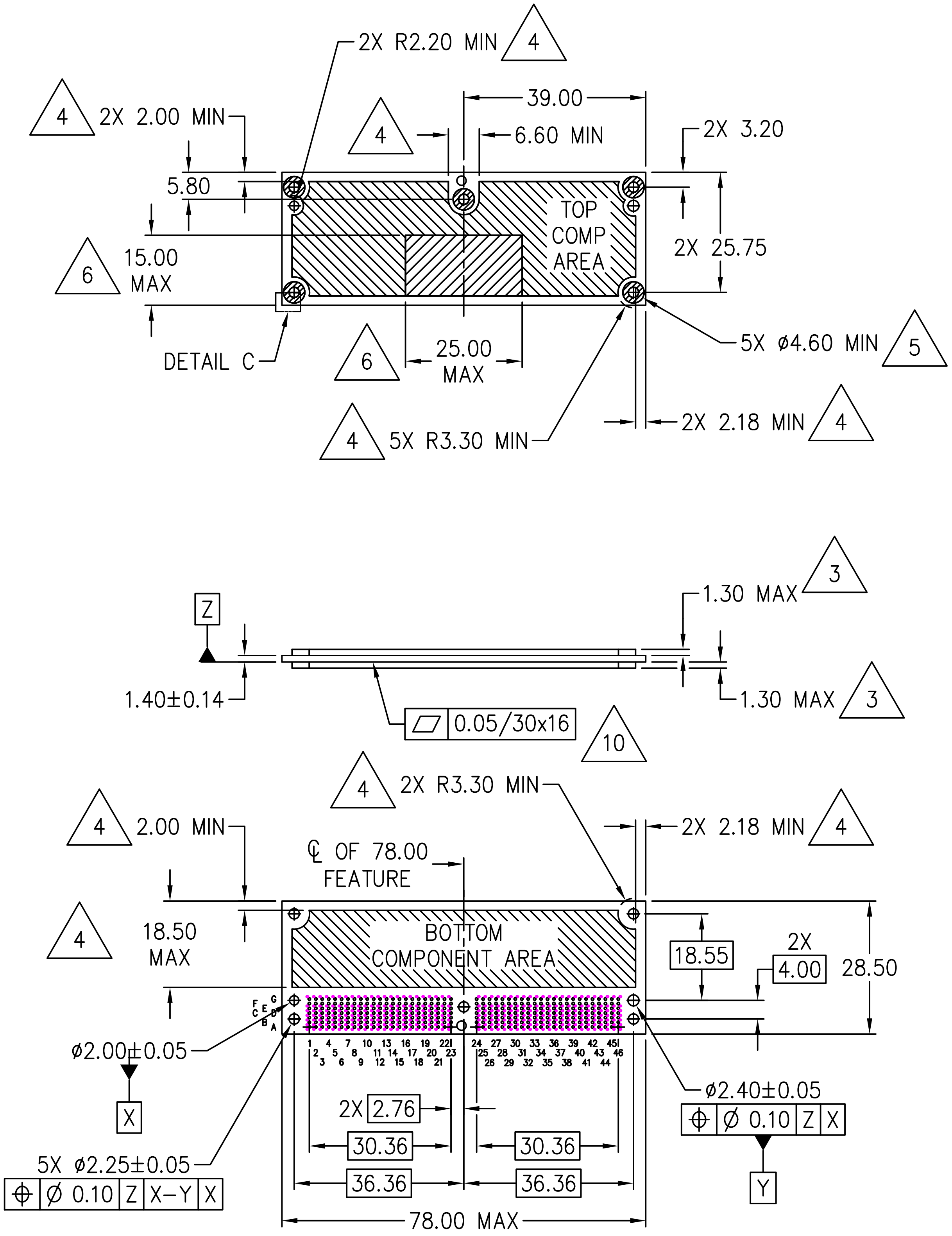
JEDEC SOLID STATE PRODUCT OUTLINE	TITLE	NUMBER	ISSUE	DATE	SHEET
	DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	MO-358	C	AUG 2025	3 OF 10



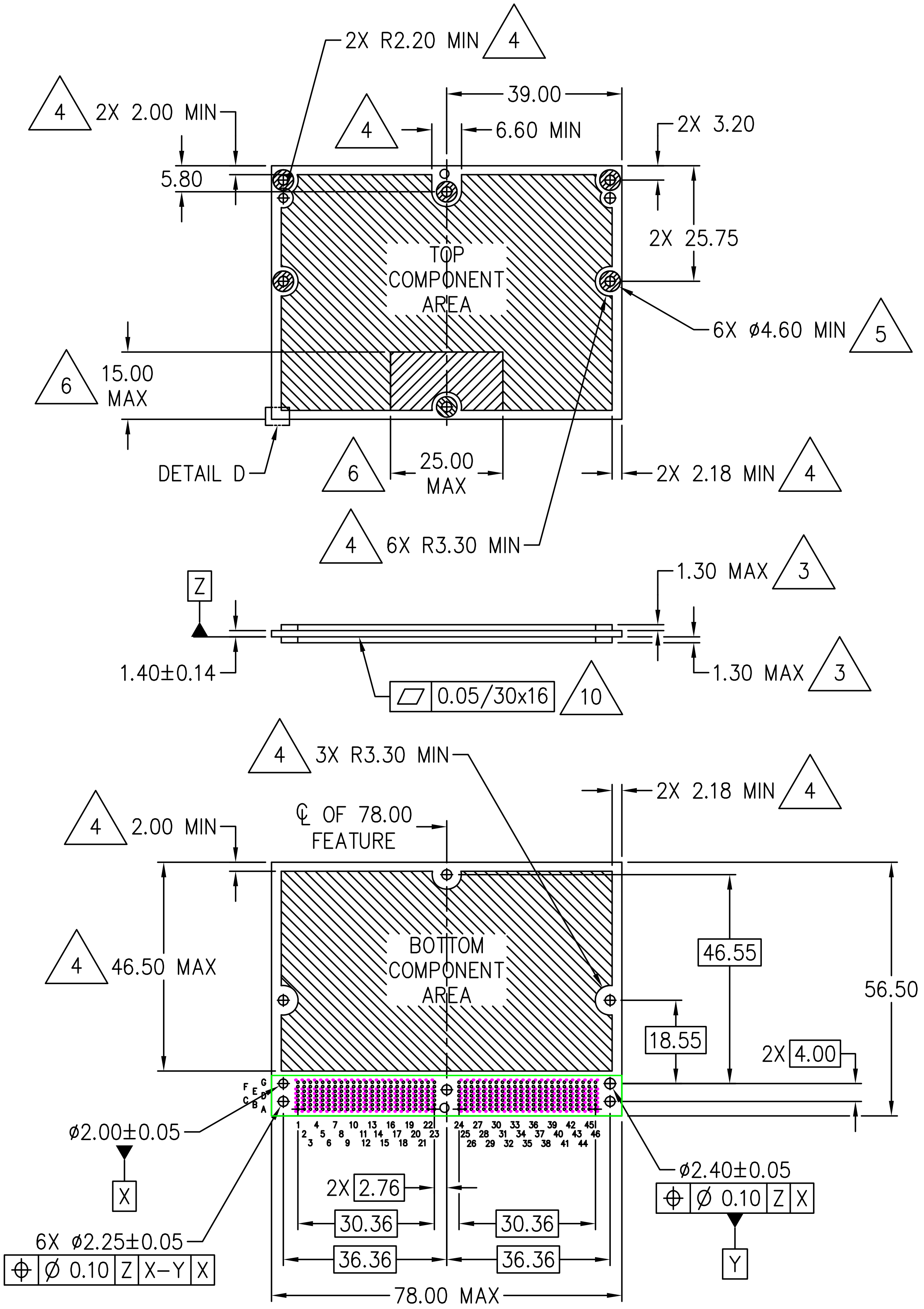
DETAIL A

DETAILED REFERENCE PCB FOOTPRINT
(APPLY TO VARIATION: AXXX/BXXX/CXXX)

JEDEC SOLID STATE PRODUCT OUTLINE Copyright © 2025 JEDEC. All rights reserved. May not be reproduced without permission.	TITLE DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	NUMBER MO-358	ISSUE C	DATE AUG 2025	SHEET 4 OF 10

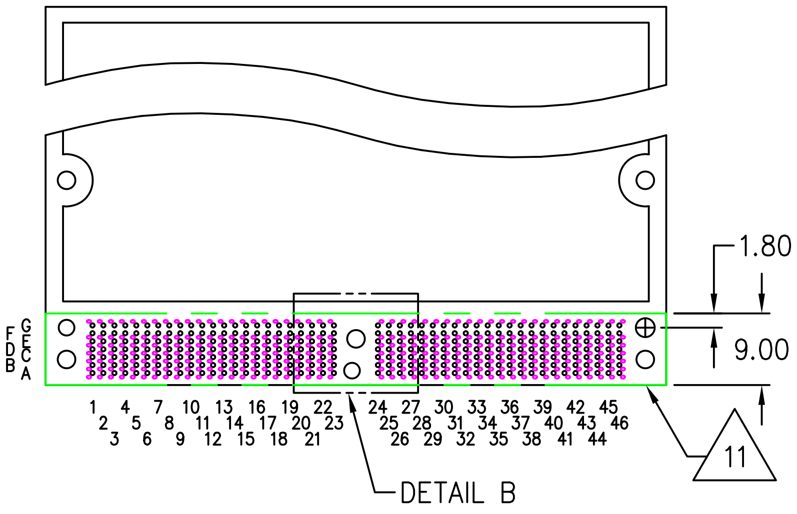


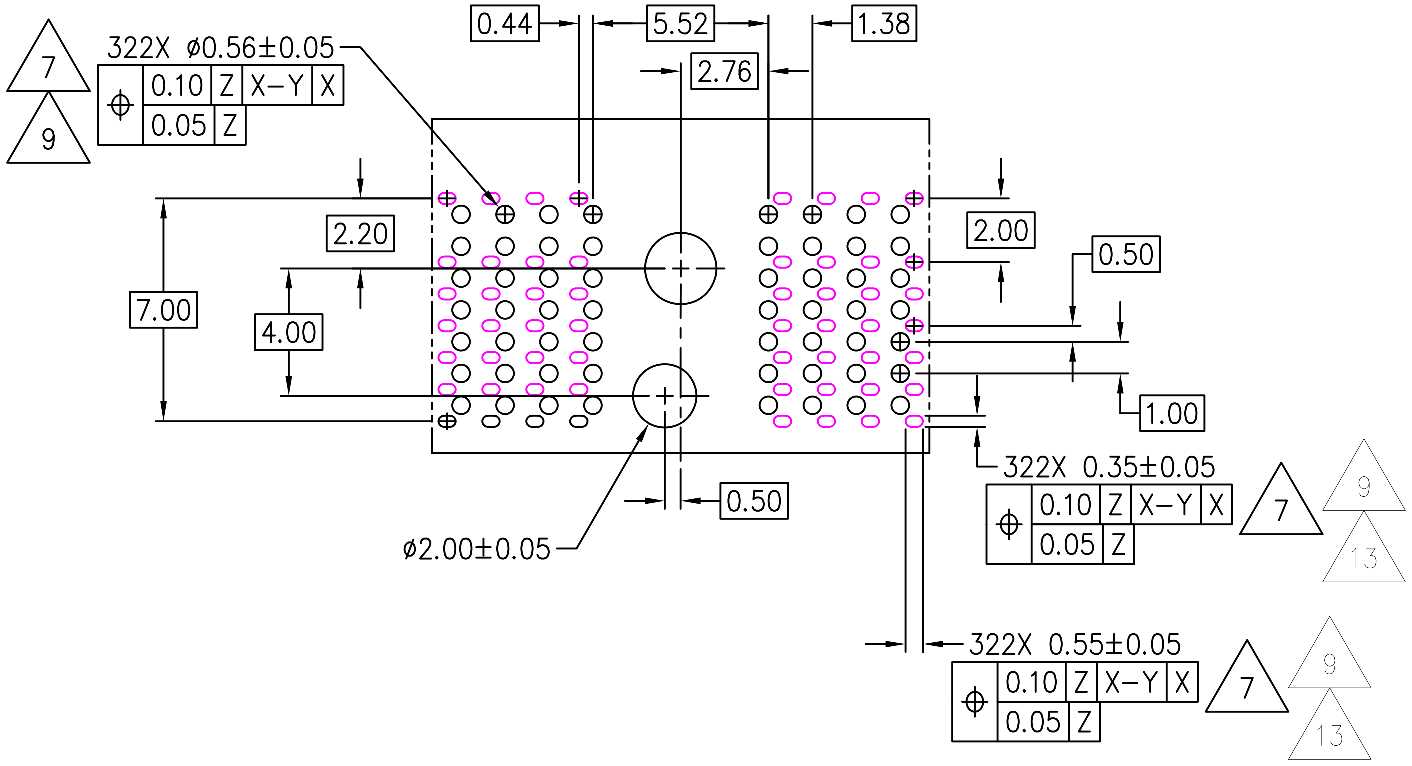
VARIATION DXXX



VARIATION EXXX

JEDEC SOLID STATE PRODUCT OUTLINE Copyright © 2025 JEDEC. All rights reserved. May not be reproduced without permission.	TITLE DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	NUMBER MO-358	ISSUE C	DATE AUG 2025	SHEET 6 OF 10

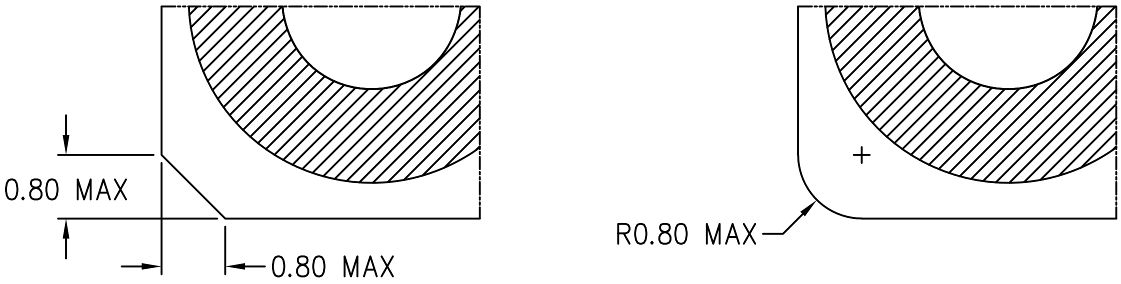




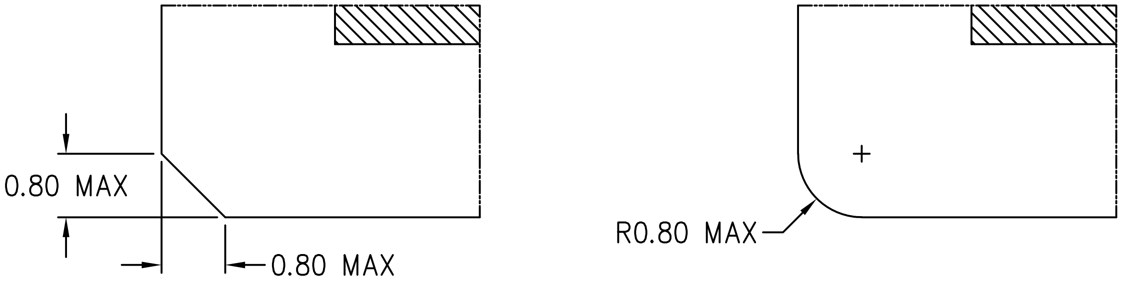
DETAIL B

DETAILED REFERENCE PCB FOOTPRINT
(APPLY TO VARIATION: DXXX/EXXX)

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE	NUMBER	ISSUE	DATE	SHEET
	DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	MO-358	C	AUG 2025	7 OF 10



DETAIL C



DETAIL D

DETAIL C AND D, TYP ALL CORNERS
ANY COMBINATION OF CHAMFER AND RADII CAN BE USED

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE	NUMBER	ISSUE	DATE	SHEET
Copyright © 2025 JEDEC. All rights reserved. May not be reproduced without permission.	DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	MO-358	C	AUG 2025	8 OF 10

NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5–2009.

2. ALL DIMENSIONS ARE IN MILLIMETERS, TOLERANCES ON ALL DIMENSIONS IS ±0.15 UNLESS OTHERWISE SPECIFIED.

3 DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON THE MODULE (LABEL NOT INCLUDED).

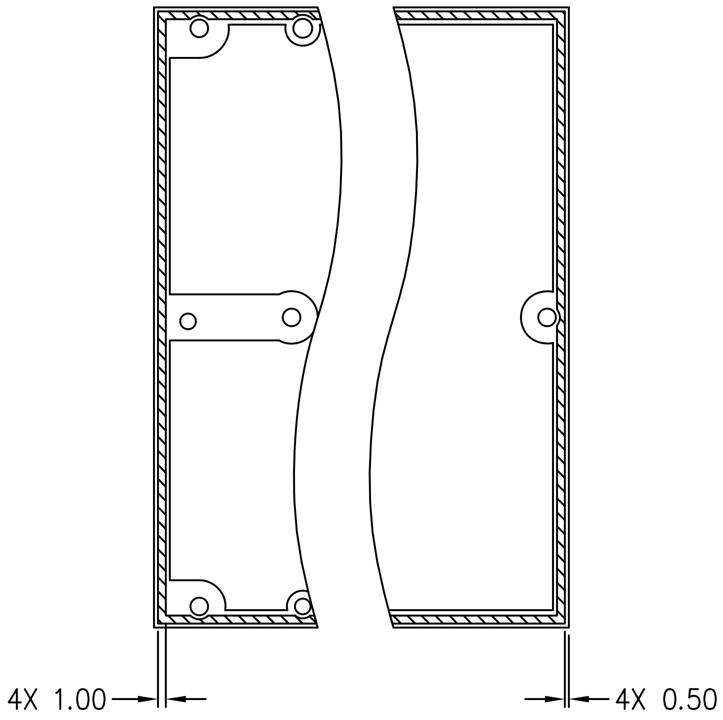
4 BORDER OF COMPONENT AREA.

5 BORDER OF VSS NET FOR MODULE RETENTION.

6 THE DIMENSION DEFINE THE BOUNDARY OF PMIC AND SPD FOR THERMAL DESIGN.

7 SURFACE TERMINAL (A.K.A. CONTACT PAD).

8. RESERVED TO ATTACH RFI/EMI SHIELD (APPLY TO VARIATION: AXXX, BXXX, CXXX, DXXX AND EXXX).



REFERENCE EXPOSED GROUND STRIP
(BOTH SIDES)

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		MO-358	C	AUG 2025	9 OF 10

NOTES CONTINUED:

9 PLATING FOR CONTACT TERMINALS ARE:
1) VARIATION Axxx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 0.25 MICROMETERS MINIMUM PALLADIUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
2) VARIATION Bxxx: GOLD PLATING 0.05 MICROMETERS MINIMUM OVER 2.00 MICROMETERS MINIMUM NICKEL.
MODULE PLATING RECOMMENDATIONS TESTED PER INDUSTRY STANDARD EIA 364-1000. RELIABILITY TESTING REQUIRES TEST MODULE, CONNECTOR, AND IDENTIFICATION OF TEST CONDITIONS.

10 ONLY APPLIES TO THE CONTACT TERMINAL AREA.

11 SOLDER MASK IS NOT ALLOWED IN THIS AREA ON THE BOTTOM COMPONENT SIDE.

13 THE OBLONG PADS (DOUBLE-D PER JEP30-P100) ARE GROUND SHIELD CONTACTS FOR THE CAMM2 CONNECTOR. THESE ARE NOT ISOLATED COPPER PATTERNS BUT INCLUDED IN THE GROUND PLANE OF BOTTOM SURFACE.

14. REFER TO JEDEC REGISTERED OUTLINE SO-032 FOR CONNECTOR DIMENSIONS.

15. SEE JESD30 FOR EXPLANATION OF PACKAGE DESIGNATOR/VARIATION.

JEDEC SOLID STATE PRODUCT OUTLINE	TITLE	NUMBER	ISSUE	DATE	SHEET
	DDR5 CAMM2, 1.38 MM X 1.00 MM PITCH MICROELECTRONIC ASSEMBLY	MO-358	C	AUG 2025	10 OF 10

STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
MO−358C−AXXX_XBMA−N736_I1p0_R78p0x40p0Z4p14	AUG 2025	14−218 14−236
MO−358C−BXXX_XBMA−N736_I1p0_R78p0x54p0Z4p14	AUG 2025	14−218 14−236
MO−358C−CXXX_XBMA−N736_I1p0_R78p0x68p0Z4p14	AUG 2025	14−218 14−236
MO−358B−DXXX_XBMA−N322_I1p0_R78p0x28p5Z4p14	JUN 2024	14−229
MO−358B−EXXX_XBMA−N322_I1p0_R78p0x56p5Z4p14	JUN 2024	14−229

TASK GROUP CONTRIBUTORS

ALIBABA (CHINA) CO. LTD
AMPHENOL CORPORATION
ARGOSY RESEARCH INC.
CHANGXIN MEMORY TECHNOLOGIES INC (CXMT)
DELL INC
FOXCONN INTERCONNECT TECHNOLOGY
HEWLETT PACKARD ENTERPRISE
HP INC
INTEL CORPORATION
LENOVO
LOTES CO, LTD
LUXSHARE–ICT, INC.
MOLEX LLC
SAMSUNG SEMICONDUCTOR
SHENZHEN DEREN ELECTRONIC CO. LTD.
SMART MODULAR TECHNOLOGIES INC.
TE CONNECTIVITY
WLCO SHENZHEN CO., LTD.

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE: A	DATE: SEPTEMBER 2023	ITEM NUMBER: 14–218

CHANGE RECORD HISTORY:

ISSUE: B	DATE: JUNE 2024	ITEM NUMBER: 14–229

LOCATION:	CHANGED FROM:	CHANGED TO:
SHEET 3	46.55	$\boxed{46.55}$
SHEETS 4 & 7		ADDED 2.20 DIMENSION
		ADDED SOLDER MASK KEEPOUT DIMENSIONS
SHEET 5	19.00 MAX 29.50	18.50 MAX 28.50
SHEET 6		ADDED ADDITIONAL HOLE AT 46.55 FROM DATUM Y
	5X Ø4.60 MIN	6X Ø4.60 MIN
	5X R3.30 MIN	6X R3.30 MIN
	5X Ø2.25±0.05	6X Ø2.25±0.05
	2X R3.30 MIN	3X R3.30 MIN
	46.00 MAX COMPONENT AREA	46.50 MAX COMPONENT AREA
SHEET 8		NEW SHEET FOR DETAILS
SHEET 10		ADDED NOTES 9, 10, 11, & 12

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

ISSUE: C	DATE: AUGUST 2025	ITEM NUMBER: 14-236

LOCATION:	CHANGED FROM:	CHANGED TO:
ALL SHEETS	1.00 MM X 1.38 MM	1.38 MM X 1.00 MM TO MATCH SO
SHEETS 1 – 4		ADDED ROW R & T TERMINALS
SHEET 4	644	736
		ADDED NOTES 9 & 13 TO OBLONG TERMINALS
SHEET 7	644	322
		ADDED NOTES 9 & 13 TO OBLONG TERMINALS
SHEET 9		ADDED (LABEL NOT INCLUDED).
SHEET 10		REMOVE NOTE 12 ADDED NOTES 13, 14, & 15